

Characteristic	Symbol	Value	Units		
Drain-Source Voltage			V_{DSS}	-30	V
Gate-Source Voltage	V _{GSS}	±12	V		
Continuous Drain Current (Note 5) V _{GS} = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	l _D	-3.0 -2.3	А
Continuous Drain Current (Note 6) V _{GS} = -10V	Steady State	$T_A = +25^{\circ}C$ $T_A = +70^{\circ}C$	I _D	-3.7 -2.9	А
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I _{DM}	-30	Α
Maximum Body Diode Continuous Current (Note 6)			I _S	-1.5	Α

Thermal Characteristics

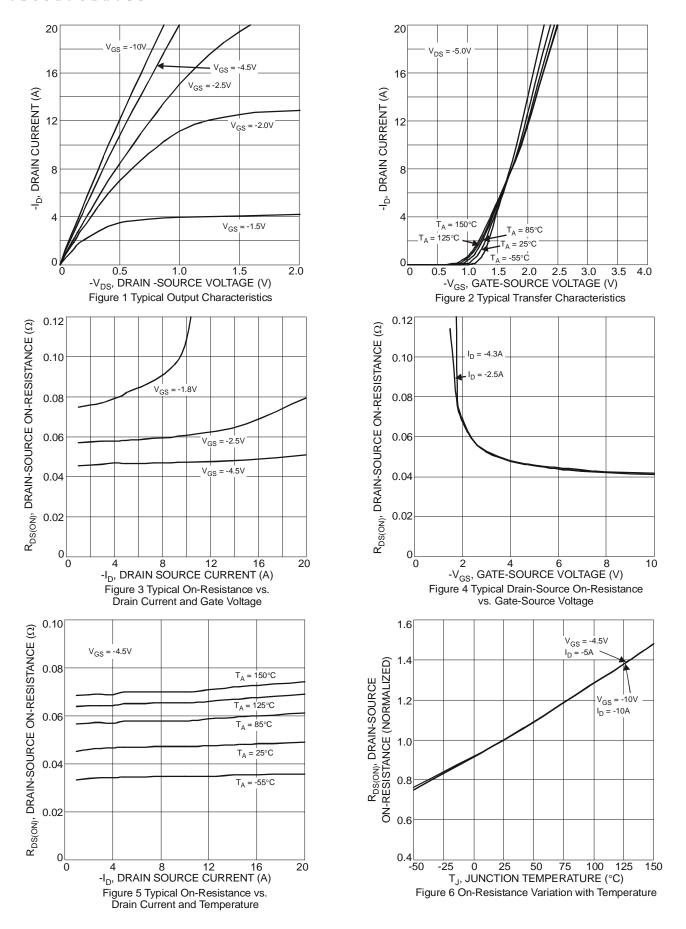
Characteristic		Symbol	Value	Units
Total Dawer Dissination	(Note 5)	0	0.8	- w
Total Power Dissipation	(Note 6)	P _D	1.2	
Thermal Resistance, Junction to Ambient	(Note 5)	-	159	°C/W
	(Note 6)	$R_{ hetaJA}$	105	
Thermal Resistance, Junction to Case	(Note 6)	R _θ JC	36	
Operating and Storage Temperature Range		$T_{J,}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

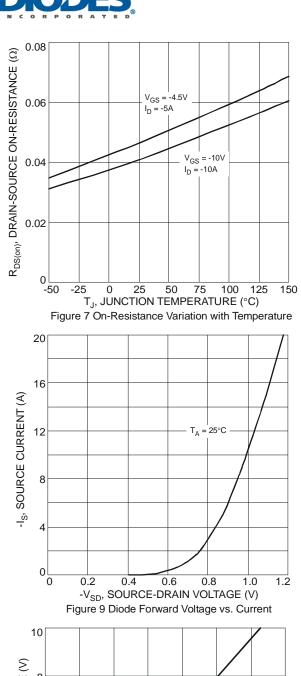
Chanastavistia	Compleal	N#:	T	Mari	11:::4	Toot Condition
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)	T 5)/	- 00	1	I	1 1/	N/ 01/ 1 050 A
Drain-Source Breakdown Voltage	BV _{DSS}	-30	-	-	V	$V_{GS} = 0V, I_D = -250\mu A$
Zero Gate Voltage Drain Current T _J = 25°C	I _{DSS}	-	-	-1.0	μΑ	$V_{DS} = -30V, V_{GS} = 0V$
Gate-Body Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	-0.5	-1.0	-1.3	V	$V_{DS} = V_{GS}$, $I_D = -250\mu A$
Static Drain-Source On-Resistance		-	41	50	mΩ	$V_{GS} = -10V, I_D = -4A$
	R _{DS} (ON)	-	47	60		$V_{GS} = -4.5V$, $I_D = -3.5A$
		-	60	85		$V_{GS} = -2.5V$, $I_D = -2.5A$
Forward Transfer Admittance	Y _{fs}	-	12	-	S	$V_{DS} = -5V, I_{D} = -4A$
Diode Forward Voltage	V_{SD}	-	-0.8	-1.0	V	$V_{GS} = 0V, I_{S} = -1A$
DYNAMIC CHARACTERISTICS (Note 8)					÷.	
Input Capacitance	C _{iss}	-	1326	-		V _{DS} = -15V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	Coss	-	103	-	pF	
Reverse Transfer Capacitance	C_{rss}	-	71	-		
Gate Resistance	Rg	-	7.3	-	Ω	$V_{DS} = 0V, V_{GS} = 0V, f = 1.0MHz$
Total Gate Charge (V _{GS} = -4.5V)	Q_g	-	11.6	-		
Total Gate Charge (V _{GS} = -10V)	Q_{g}	-	25.1	-	nC	V _{DD} = -15V, I _D = -4A
Gate-Source Charge	Q_{gs}	-	2	-	nC nC	
Gate-Drain Charge	Q_{gd}	-	1.7	-		
Turn-On Delay Time	t _{D(on)}	-	8	-		
Turn-On Rise Time	t _r	-	13	-	nS	$V_{DS} = -15V$, $V_{GS} = -10V$,
Turn-Off Delay Time	t _{D(off)}	-	71	-] 113	$R_{GEN} = 6\Omega$, $R_L = 3.75\Omega$
Turn-Off Fall Time	t _f	-	38	-		

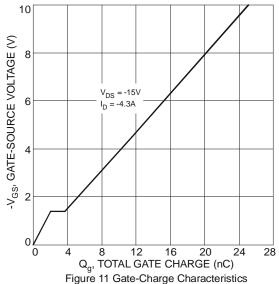
- 5. Device mounted on FR-4 PC board, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper pad layout
- 7 .Short duration pulse test used to minimize self-heating effect.
 8. Guaranteed by design. Not subject to production testing











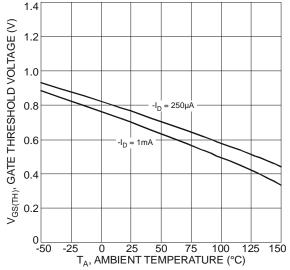
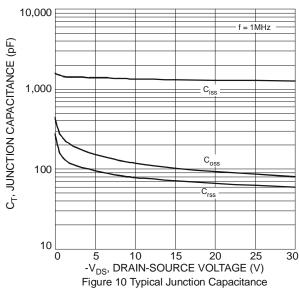
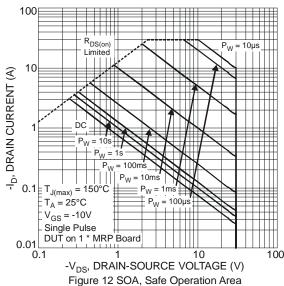
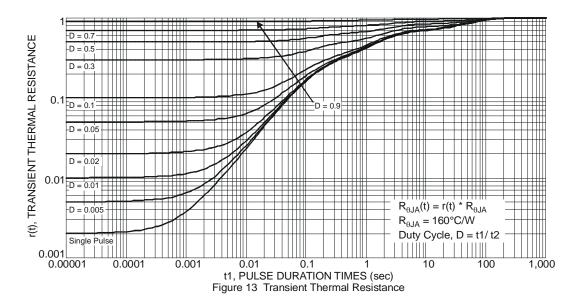


Figure 8 Gate Threshold Variation vs. Ambient Temperature



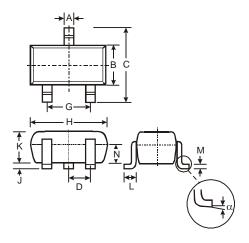






Package Outline Dimensions

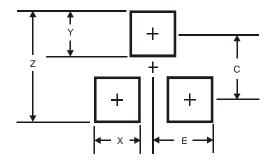
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SC59						
Dim	Min	Max	Тур			
Α	0.35	0.50	0.38			
В	1.50	1.70	1.60			
С	2.70	3.00	2.80			
D	-	-	0.95			
G	-	-	1.90			
Н	2.90	3.10	3.00			
J	0.013	0.10	0.05			
K	1.00	1.30	1.10			
L	0.35	0.55	0.40			
M	0.10	0.20	0.15			
N	0.70	0.80	0.75			
α	0°	8°	-			
All Dimensions in mm						

Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
Z	3.4
Х	0.8
Υ	1.0
С	2.4
Е	1.35



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